



Drill Map:

- x 0.406mm / 0.0160" (13 holes)
- o 0.800mm / 0.0315" (4 holes)
- + 0.991mm / 0.0390" (4 holes)
- 1.000mm / 0.0394" (2 holes)
- ◇ 1.067mm / 0.0420" (10 holes)
- ⊠ 1.100mm / 0.0433" (4 holes)
- * 1.194mm / 0.0470" (4 holes)
- ⊠ 1.295mm / 0.0510" (4 holes)
- ⊠ 2.700mm / 0.1063" (4 holes) (not plated)
- ⊕ 3.400mm / 0.1339" (4 holes) (not plated)

NOTES:

- Layers: 2
- PCB Thickness: 1.6 mm
- PCB Color: GREEN
- Material Type: FR-4 TG155
- Surface Finish: HASL
- Outer Copper Weight: 1 oz
- Impedance Control: NO
- Layer Stackup: xxxx
- Via Covering: Plugged
- Min Via Hole Size / Diameter: 0.406 mm / 0.81 mm
- Board Outline Tolerance: +/- 0.2 mm
- Silk Screen: INK-JET/SCREEN PRINTING
- Stencil Framework: YES
- Sencil Polishing: Electropolishing
- Fiducials: Etched Through
- Engrave Text

BOARD CHARACTERISTICS

Copper Layer Count:	2	Board Thickness:	62.68 mils
Board overall dimensions:	3937.00 mils x 3110.00 mils		
Min track/spacing:	10.00 mils / 7.73 mils	Min hole diameter:	16.00 mils
Copper Finish:	HAL SnPb	Impedance Control:	No
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	White	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Green	3.3	0
F.Cu	copper		1.38 mils		1	0
Dielectric 1	core	FR4	59.12913 mils	FR4 natural	4.5	0.02
B.Cu	copper		1.38 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	White	1	0